

**ABSTRACT**

A packaging structure for optoelectronic components is formed by a first body, of semiconductor material, and a second body, of semiconductor material, fixed to a first face of said first body. A through window is formed in the second body and exposes a portion of the first face of the first body, whereon at least one optoelectronic component is fixed. Through connection regions extend through the first body and are in electrical contact with the optoelectronic component. The through connection regions are insulated from the rest of the first body via through insulation regions. Contact regions are arranged on the bottom face of the first body and are connected to said optoelectronic component via the through connection regions.